

N-MOSFET 100V 4mΩ 122A

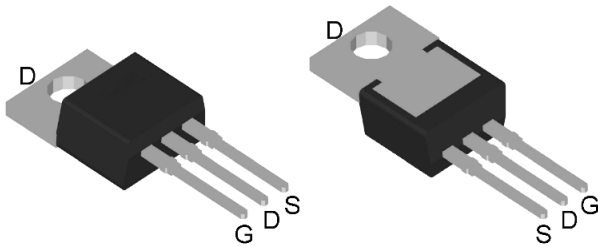
Product Summary

- V_{DS} 100V
- I_D 122A
- R_{DS(ON)} (at V_{GS}=10V) <5mΩ (Typ:4 mΩ)

Naming convention

M	G	P	0	4	0	N	1	0	A	N
Megain		B: PDFN3X3 C: PDFN5X6 P: TO220 H: TO263 S: SOP8 D: TO252	ROSON Typ. @V _{GS} =10V			N: N P: P C: N+P D: N+N	10: 100V 06: 60V 08: 80V 04: 40V 03: 30V	A:V _{GS} 20/-12 w/o A:V _{GS} ±20	L:V _{th} (1~2.5V) N:V _{th} (2~4V)	

Pin configuration



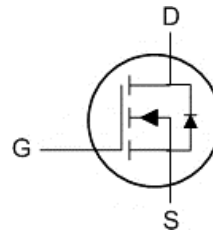
Features

- Fast switching speed
- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

Application

- High Efficiency Synchronous Rectification in SMPS
- Hard Switched and High Frequency Circuits
- USB Power Delivery (USB PD)

Symbol



Ordering Information

Order code	Package	Form	Quantity (PCS)	Marking
MGP040N10N	TO220	Tube	50 / Tube	MGP040N10N

Absolute Maximum Ratings

T_C=25°C Unless Otherwise Noted.

Symbol	Parameter	Value	Units
V _{DS}	Drain-Source Voltage	100	V
V _{GS}	Gate-Source Voltage	± 20	V
I _D	Drain Current – Continuous ¹ (T _C =25°C)	122	A
	Drain Current – Continuous (T _C =100°C)	102	
	Drain Current – Continuous (T _A =25°C)	20.4	
	Drain Current – Continuous (T _A =70°C)	16.3	
P _D	Power Dissipation(T _C =25°C)	125	W
	Power Dissipation (T _C =100°C)	50	
	Power Dissipation(T _A =25°C)	2.0	
	Power Dissipation (T _A =70°C)	1.3	
I _{DM}	Drain Current – Pulsed ¹	305	A
I _S	Diode Continuous Forward Current (T _C =25°C)	113	A
I _{AS}	Single Pulse Avalanche Current ² (L=0.1mH)	56	A
	Single Pulse Avalanche Current ² (L=0.5mH)	31	
E _{AS}	Single Pulse Avalanche Energy ² (L=0.1mH)	157	mJ
	Single Pulse Avalanche Energy ² (L=0.5mH)	240	
T _J	Operating Junction Temperature Range	-55 to 150	°C
T _{STG}	Storage Temperature Range	-55 to 150	°C

■ Thermal Characteristics

Symbol	Parameter	Max.	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	62.5	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case ³	1	$^{\circ}\text{C}/\text{W}$

■ Electrical Characteristics

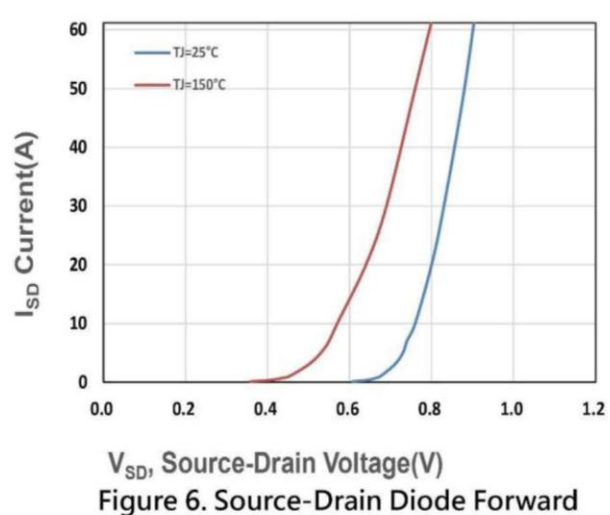
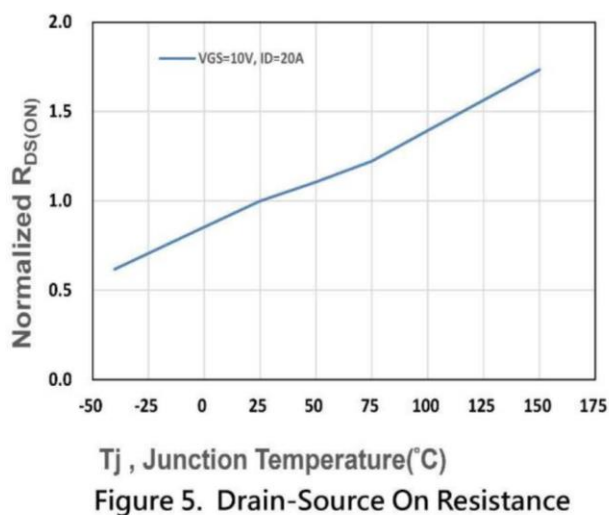
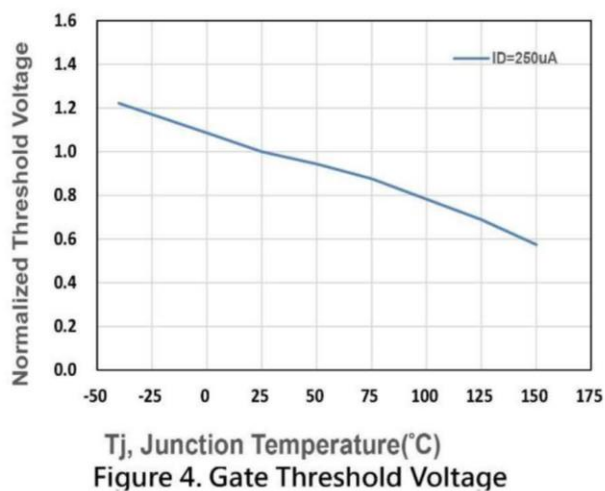
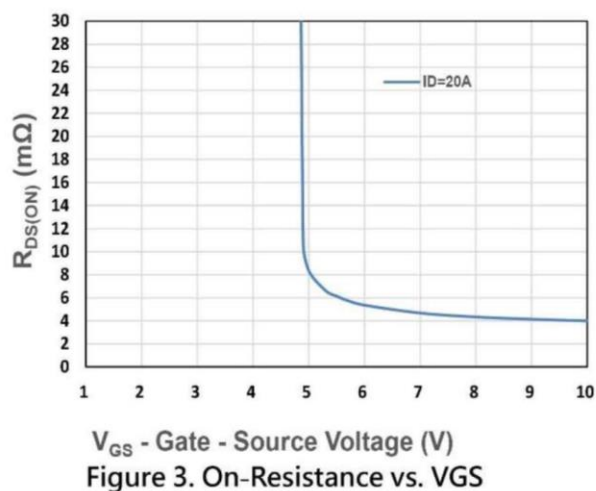
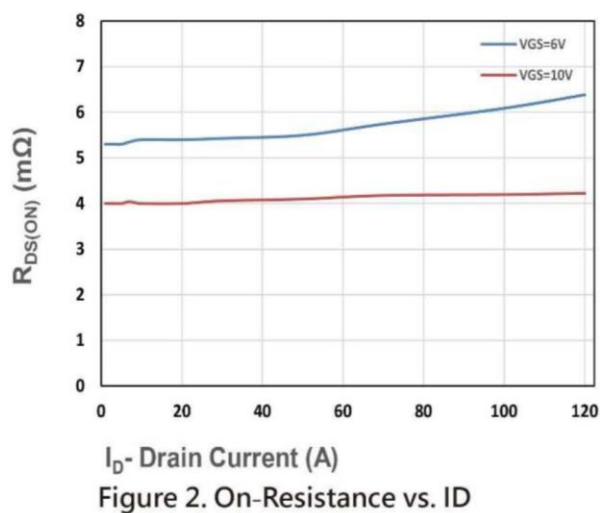
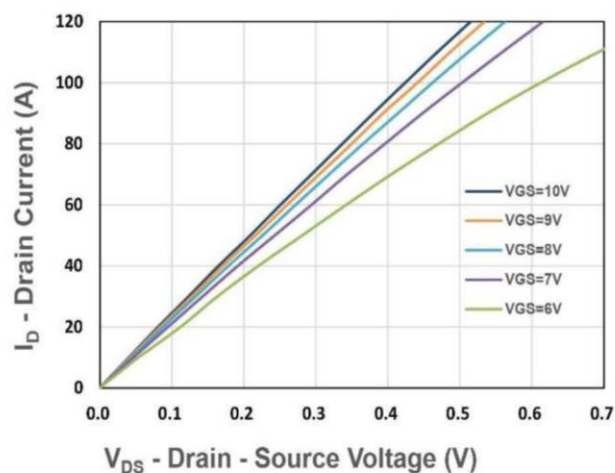
$T_J=25^{\circ}\text{C}$ Unless Otherwise Noted.

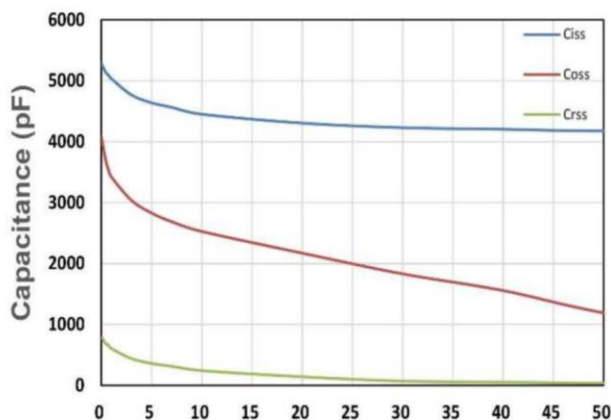
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
Static Electrical Characteristics						
B _V D _{SS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	100	-	-	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V, V _{GS} =0V	-	-	1	uA
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	2	3	4	V
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)}	Static Drain-Source On-Resistance ⁴	V _{GS} =10V, I _D =20A	-	4	4.8	mΩ
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =10A	-	40	-	S
Dynamic and switching Characteristics						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, F=1MHz	-	0.7	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =50V, F=1MHz	-	4175	-	pF
C _{oss}	Output Capacitance		-	1190	-	
C _{rss}	Reverse Transfer Capacitance		-	35	-	
t _{d(ON)}	Turn-On Delay Time	V _{GS} =10V, V _{DS} =25V, I _D =1A, R _G =3Ω	-	12.8	-	nS
T _r	Rise Time		-	6.3	-	
T _{d(off)}	Turn-off Delay Time		-	35	-	
T _f	Turn-off Fall Time		-	65	-	
Q _g	Total Gate Charge	V _{GS} =6V, V _{DS} =50V, I _D =20A	-	47	-	nC
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =50V, I _D =20A	-	72.8	-	
Q _{gs}	Gate-Source Charge		-	21.5	-	
Q _{gd}	Gate-Drain Charge		-	20.6	-	
Source-Drain Characteristics						
V _{SD}	Diode Forward Voltage ⁴	I _S =10A, V _{GS} =0V	-	0.75	1.1	V
t _{rr}	Reverse Recovery Time	I _F =10A, V _R =50V	-	40.4	-	nS
Q _{rr}	Reverse Recovery Charge	di _F /dt=100A/μs	-	80.2	-	nC

Note :

1. Max. current is limited by bonding wire
2. UIS tested and pulse width are limited by maximum junction temperature 150°C
3. Surface Mounted on 1in^2 FR-4 board with 1oz
4. Pulse test (pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$).
5. Guaranteed by design, not subject to production testing.

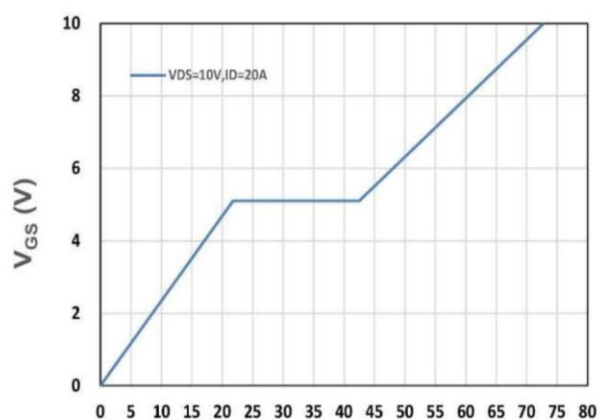
■ Typical Characteristics





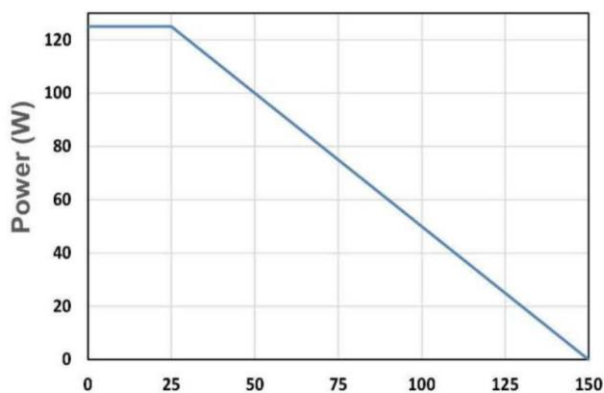
V_{DS} - Drain - Source Voltage (V)

Figure 7. Capacitance



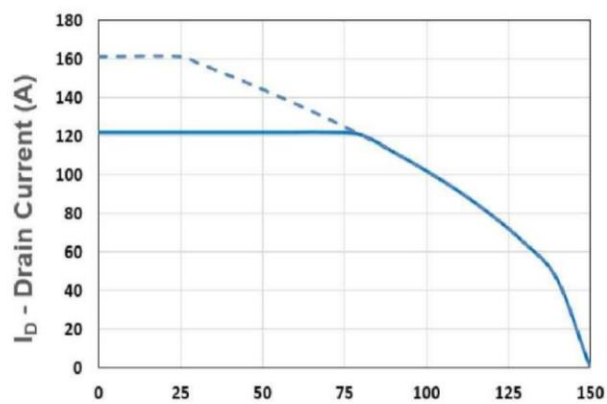
Q_g , Total Gate Charge (nC)

Figure 8. Gate Charge Characteristics



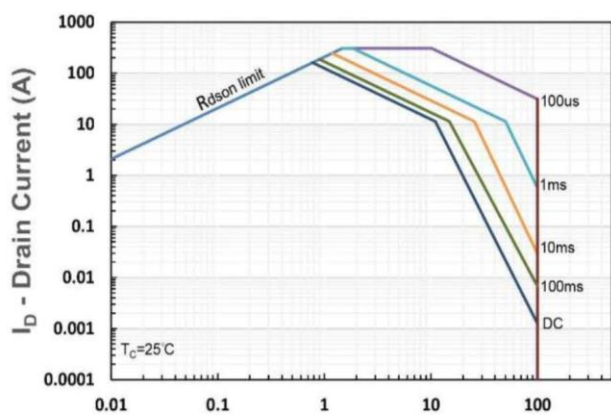
T_c - Case Temperature (°C)

Figure 9. Power Dissipation



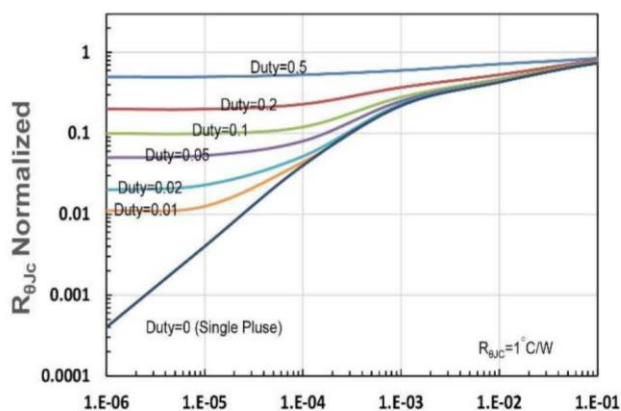
T_c - Case Temperature (°C)

Figure 10. Drain Current



V_{DS} - Drain-Source Voltage (V)

Figure 11. Safe Operating Area



t_1 , Square Wave Pulse Duration (s)

Figure 12. $R_{\theta Jc}$ Transient Thermal Impedance

■ Package size

Unit: mm。

TO220:

